### Multilayer Ceramic Chip Capacitors

# 1 of 3 Creation Date : October 12, 2017 (GMT)

### C1005X5R1A335K050BC



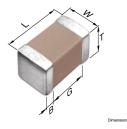






#### **TDK item description** C1005X5R1A335KT\*\*\*\*

Applications	Commercial Grade	
Feature	General General (Up to 50V)	
Series	C1005 [EIA 0402]	
Status	Production	



	Size	
Length(L)	1.00mm ±0.10mm	
Width(W)	0.50mm ±0.10mm	
Thickness(T)	0.50mm ±0.10mm	
Terminal Width(B)	0.10mm Min.	
Terminal Spacing(G)	0.30mm Min.	
Recommended Land Pattern (PA)	0.30mm to 0.50mm	
Recommended Land Pattern (PB)	0.35mm to 0.45mm	
Recommended Land Pattern (PC)	0.40mm to 0.60mm	

Electrical Characteristics		
Capacitance	3.3µF ±10%	
Rated Voltage	10VDC	
Temperature Characteristic	X5R(±15%)	
Dissipation Factor (Max.)	10%	
Insulation Resistance (Min.)	30ΜΩ	

Other	
Soldering Method	Reflow
AEC-Q200	No
Packing	Punched (Paper)Taping [180mm Reel]
Package Quantity	10000pcs

<sup>!</sup> Images are for reference only and show exemplary products. ! This PDF document was created based on the data listed on the TDK Corporation website.

<sup>!</sup> All specifications are subject to change without notice.

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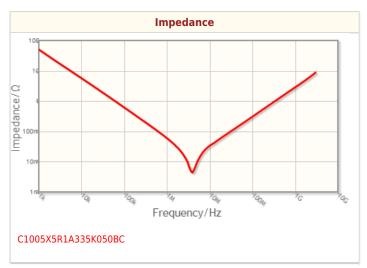


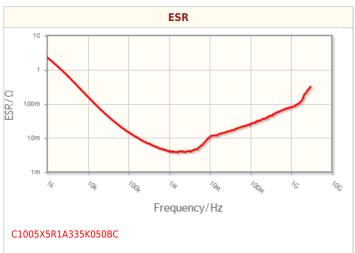


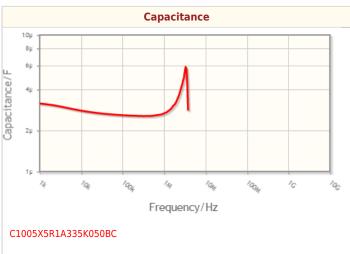


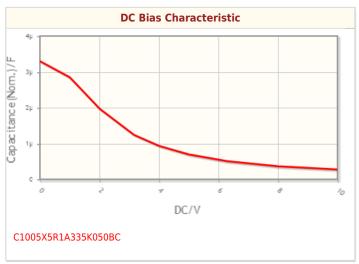


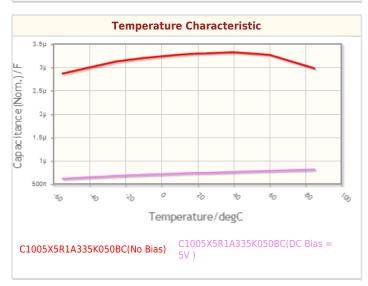
## Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

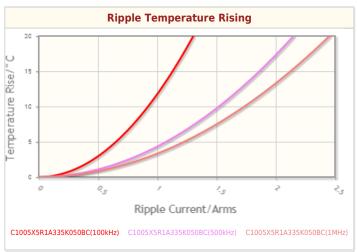












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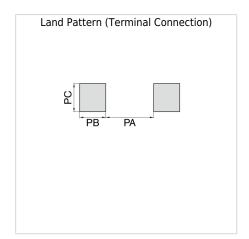






# **Associated Images**

C1005X5R1A335K050BC



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